

REMARKS

In view of the foregoing amendments, Applicant respectfully requests favorable consideration and early passage to issue of the present application.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee (mail label #EL611014165US) in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 25, 2001:

Dorothy Jenkins

Name of Person Mailing Correspondence

Dorothy Jenkins

Signature

May 25, 2001

Date of Signature

SIW:lac

Respectfully submitted,

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APPENDIX A
"Clean" Version of Each Paragraph/Section/Claim
37 C.F.R. § 1.121(b)(ii) and (c)(i)

TITLE:

Replacement title at page 1, line 1:

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

SPECIFICATION:

New section beginning at page 1, line 2 (after the title):

CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional of U.S. Patent Application Serial No. 09/407,910, filed September 29, 1999 in the name of Takahisa Yamaha and entitled BONDING PAD STRUCTURE OF SEMICONDUCTOR DEVICE.

APPENDIX B
Version with Markings to Show Changes Made
37 C.F.R. § 1.121(b)(iii) and (c)(ii)

TITLE:

Title at page 1, line 1:

[BONDING PAD STRUCTURE OF] METHOD FOR MANUFACTURING A
SEMICONDUCTOR DEVICE